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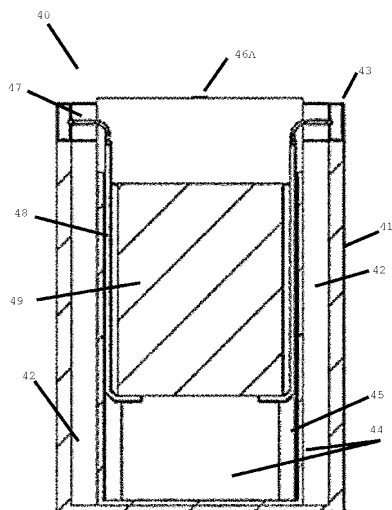


FIG. 4C

(57) Abstract: The invention relates to an immersion cooling system for controlling the temperature of a heat generating hardware component. The immersion cooling system supplies cooling liquid to a reservoir that has hardware component positions. In that reservoir the cooling liquid is held and hardware component are immersed. A cooling liquid recovery allows discharge of cooling liquid. The hardware is held in positions that are positioned in a flow path of the cooling liquid from the one or more supply points to the outlet. The supply can be adapted to the hardware component, e.g. a heat profile of the hardware component in use. Extra supplies can be provided when extra hardware components are added. And distal parts of the supply can be removed and closed if hardware component are removed from the reservoir. The cooling liquid supply has one or more nozzles for each multiple hardware positions, the one or more nozzles configured to supply cooling liquid directed at the hardware position of the hardware component.

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